**FEATURES**

- Single Resistor Programmable V<sub>OUT</sub>
- ±1% I<sub>SET</sub> Accuracy
- Tight V<sub>OUT</sub> Regulation Independent of V<sub>OUT</sub> Voltage
- Easy to Parallel for Higher Current and Heat Spreading
- Wide V<sub>OUT</sub> Range 0V to VIN – 0.5V
- High Efficiency: Up to 96%
- 1.5A Output Current
- Adjustable Frequency: 200kHz to 4MHz
- 4V to 15V VIN Range
- Current Mode Operation for Excellent Line and Load Transient Response
- Zero Supply Current in Shutdown
- Available in Thermally Enhanced 12-Pin (3mm × 3mm) DFN and MSOP Packages

**APPLICATIONS**

- Voltage Tracking Supplies
- Point-of-Load Power Supplies
- Portable Instruments
- Distributed Power Systems

**DESCRIPTION**

The LTC®3600 is a high efficiency, monolithic synchronous buck regulator whose output is programmed with just one external resistor. The accurate internally generated 50µA current source on the ISET pin allows the use of a single external resistor to program an output voltage that ranges from 0V to 0.5V below VIN. The V<sub>OUT</sub> voltage feeds directly back to the error amplifier in unity gain fashion and equals the ISET voltage. The operating supply voltage range is 4V to 15V, making it suitable for dual lithium-ion battery and 5V or 12V input point-of-load power supply applications.

The operating frequency is synchronizable to an external clock or programmable from 200kHz to 4MHz with an external resistor. High switching frequency allows the use of small surface mount inductors. The unique constant on-time architecture is ideal for operating at high frequency in high step-down ratio applications that also demand fast load transient response.

© LT, LTC, LTM, Linear Technology, the Linear logo and OPTI-LOOP are registered trademarks and Hot Swap is a trademark of Linear Technology Corporation. All other trademarks are the property of their respective owners. Protected by U.S. Patents, including 5481178, 5705919, 5847554, 6580258.
LTC3600

**ABSOLUTE MAXIMUM RATINGS** (Notes 1, 5)

- **VIN, SW Voltage**: –0.3V to 16V
- **SW Transient Voltage (Note 6)**: –2V to 21V
- **VOUT, ISET Voltage**: 0V to VIN
- **BOOST Voltage**: –0.3V to VIN + INTVCC
- **RUN Voltage**: –0.3V to 12V
- **INTVCC Voltage**: –0.3V to 7V
- **ITH, RT Voltage**: –0.3V to INTVCC
- **MODE/SYNC, PGFB, PGOOD Voltage**: –0.3V to INTVCC

**Operating Junction Temperature Range** (Notes 2, 5): –40°C to 125°C

**MSE Package Lead Temperature** (Soldering, 10 sec): 300°C

**PIN CONFIGURATION**

**ORDER INFORMATION**

<table>
<thead>
<tr>
<th>LEAD FREE FINISH</th>
<th>TAPE AND REEL</th>
<th>PART MARKING*</th>
<th>PACKAGE DESCRIPTION</th>
<th>TEMPERATURE RANGE</th>
</tr>
</thead>
<tbody>
<tr>
<td>LTC3600EDD#PBF</td>
<td>LTC3600EDD#TRPBF</td>
<td>LFXB</td>
<td>12-Lead (3mm × 3mm) Plastic DFN</td>
<td>–40°C to 125°C</td>
</tr>
<tr>
<td>LTC3600IDD#PBF</td>
<td>LTC3600IDD#TRPBF</td>
<td>LFXB</td>
<td>12-Lead (3mm × 3mm) Plastic DFN</td>
<td>–40°C to 125°C</td>
</tr>
<tr>
<td>LTC3600EMSE#PBF</td>
<td>LTC3600EMSE#TRPBF</td>
<td>3600</td>
<td>12-Lead Plastic MSOP</td>
<td>–40°C to 125°C</td>
</tr>
<tr>
<td>LTC3600IMSE#PBF</td>
<td>LTC3600IMSE#TRPBF</td>
<td>3600</td>
<td>12-Lead Plastic MSOP</td>
<td>–40°C to 125°C</td>
</tr>
</tbody>
</table>

Consult LTC Marketing for parts specified with wider operating temperature ranges. *The temperature grade is identified by a label on the shipping container. Consult LTC Marketing for information on non-standard lead based finish parts.

For more information on lead free part marking, go to: [http://www.linear.com/leadfree/](http://www.linear.com/leadfree/)

For more information on tape and reel specifications, go to: [http://www.linear.com/tapeandreel/](http://www.linear.com/tapeandreel/). Some packages are available in 500 unit reels through designated sales channels with #TRMPBF suffix.

Downloaded from Arrow.com.
### Electrical Characteristics

The ● denotes the specifications which apply over the specified operating junction temperature range, otherwise specifications are at $T_A = 25^\circ C$ (Note 2). $V_{IN} = 12V$, unless otherwise noted.

<table>
<thead>
<tr>
<th>SYMBOL</th>
<th>PARAMETER</th>
<th>CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNITS</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{IN}$</td>
<td>$V_{IN}$ Supply Range</td>
<td></td>
<td>4</td>
<td>15</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>$I_{SET}$</td>
<td>$I_{SET}$ Reference Current</td>
<td></td>
<td>49.5</td>
<td>50</td>
<td>50.5</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>●</td>
<td>49.3</td>
<td>50</td>
<td>51</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td>$I_{SET}$ Line Regulation</td>
<td>●</td>
<td>0.02</td>
<td>0.05</td>
<td>%/V</td>
<td></td>
</tr>
<tr>
<td></td>
<td>$I_{SET}$ DROP_OUT Voltage</td>
<td>$I_{SET} &gt; 45\mu A$, $V_{IN} - V_{SET}$</td>
<td>340</td>
<td>mV</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$I_{SET}$ Load Regulation</td>
<td>$I_{OUT} = 0$ to $1.5A$</td>
<td>0.25</td>
<td>µA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Error Amp Input Offset</td>
<td>(Note 4)</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Error Amp Load Regulation</td>
<td>$V_{ISET} = 0$, $R_{OUT} = 0$</td>
<td>●</td>
<td>0.05</td>
<td>0.1</td>
<td>%</td>
<td></td>
</tr>
<tr>
<td>$g_{m(EA)}$</td>
<td>Error Amplifier Transconductance</td>
<td></td>
<td>0.63</td>
<td>0.9</td>
<td>mS</td>
<td></td>
</tr>
<tr>
<td>$I_{ON(MIN)}$</td>
<td>Minimum On-Time</td>
<td></td>
<td>30</td>
<td>ns</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$I_{OFF(MIN)}$</td>
<td>Minimum Off-Time</td>
<td></td>
<td>130</td>
<td>ns</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$I_{LIM}$</td>
<td>Current Limit</td>
<td>●</td>
<td>1.6</td>
<td>2</td>
<td>2.4</td>
<td>A</td>
</tr>
<tr>
<td></td>
<td>Negative Current Limit</td>
<td></td>
<td>–0.9</td>
<td>A</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$R_{TOP}$</td>
<td>Top Power NMOS On-Resistance</td>
<td></td>
<td>200</td>
<td>mΩ</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$R_{BOTTOM}$</td>
<td>Bottom Power NMOS On-Resistance</td>
<td></td>
<td>100</td>
<td>mΩ</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$V_{UVLO}$</td>
<td>$INTV_{CC}$ Undervoltage Lockout Threshold</td>
<td>$INTV_{CC}$ Rising</td>
<td>3.45</td>
<td>3.7</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td></td>
<td>$UVLO$ Hysteresis</td>
<td>$INTV_{CC}$ Falling</td>
<td>150</td>
<td>mV</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$V_{RUN}$</td>
<td>Run Threshold</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Run Hysteresis</td>
<td>$R_{RUN} = 12V$</td>
<td>●</td>
<td>1.55</td>
<td>1.8</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$R_{RUN}$ Falling</td>
<td>0.13</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$V_{INTVCC}$</td>
<td>Internal $V_{CC}$ Voltage</td>
<td>$5.5V &lt; V_{IN} &lt; 15V$</td>
<td>4.8</td>
<td>5</td>
<td>5.4</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>$INTV_{CC}$ Load Regulation</td>
<td>$I_{LOAD} = 0mA$ to $20mA$</td>
<td>0.3</td>
<td>%</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$O_{V}$</td>
<td>Output Overvoltage PGOOD Upper Threshold</td>
<td>PGFB Rising</td>
<td>0.620</td>
<td>0.645</td>
<td>0.680</td>
<td>V</td>
</tr>
<tr>
<td>$U_{V}$</td>
<td>Output Undervoltage PGOOD Lower Threshold</td>
<td>PGFB Falling</td>
<td>0.520</td>
<td>0.555</td>
<td>0.590</td>
<td>V</td>
</tr>
<tr>
<td>PGOOD Hysteresis</td>
<td>PGFB Returning</td>
<td>10</td>
<td>mV</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PGOOD Pull-Down Resistance</td>
<td>$1mA$ Load</td>
<td>200</td>
<td>Ω</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PGOOD Leakage Current</td>
<td>PGOOD = 5V</td>
<td>1</td>
<td>µA</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>$V_{MODE/SYNC}$</td>
<td>$MODE/SYNC$ Threshold</td>
<td>$MODE$ $V_{IL(MAX)}$</td>
<td>4.3</td>
<td>0.4</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$MODE$ $V_{IH(MIN)}$</td>
<td>2.5</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$SYNC$ $V_{IH(MIN)}$</td>
<td>0.4</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$SYNC$ $V_{IL(MAX)}$</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$MODE/SYNC$ Pin Current</td>
<td>$MODE = 5V$</td>
<td>9.5</td>
<td>µA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$f_{OSC}$</td>
<td>Switching Frequency</td>
<td>$R_T = 36.1k$</td>
<td>●</td>
<td>0.92</td>
<td>1</td>
<td>1.06</td>
</tr>
<tr>
<td>$V_{OUT}$ Pin Resistance to Ground</td>
<td></td>
<td></td>
<td>600</td>
<td>kΩ</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$V_{INOV}$</td>
<td>$V_{IN}$ Overvoltage Lockout</td>
<td>$V_{IN}$ Rising</td>
<td>17.5</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{IN}$ Falling</td>
<td>16</td>
<td>V</td>
<td></td>
<td></td>
</tr>
<tr>
<td>$I_0$</td>
<td>Input DC Supply Current Discontinuous Shutdown</td>
<td>(Note 3)</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$Mode = 0$, $R_T = 36.1k$</td>
<td>700</td>
<td>1100</td>
<td>µA</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$Run = 0$</td>
<td>0</td>
<td>1.5</td>
<td>µA</td>
<td></td>
</tr>
</tbody>
</table>
ELECTRICAL CHARACTERISTICS

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime. Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

Note 2: The LTC3600 is tested under pulsed load conditions such that $T_J = T_A$. The LTC3600E is guaranteed to meet performance specifications from 0°C to 85°C junction temperature. Specifications over the −40°C to 125°C operating junction temperature range are assured by design, characterization and correlation with statistical process controls. The LTC3600I is guaranteed over the full −40°C to 125°C operating junction temperature range. Note that the maximum ambient temperature consistent with these specifications is determined by specific operating conditions in conjunction with board layout, the rated package thermal impedance and other environmental factors. The junction temperature ($T_J$ in °C) is calculated from the ambient temperature ($T_A$ in °C) and power dissipation ($P_D$ in watts) according to the formula:

$$T_J = T_A + (P_D \cdot \theta_{JA})$$

where $\theta_{JA}$ (in °C/W) is the package thermal impedance.

Note 3: Dynamic supply current is higher due to the internal gate charge being delivered at the switching frequency.

Note 4: The LTC3600 is tested in a feedback loop that adjusts $V_{OUT}$ to achieve a specified error amplifier output voltage ($I_{TM}$).

Note 5: This IC includes overtemperature protection that is intended to protect the device during momentary overload conditions. Junction temperature will exceed 125°C when overtemperature protection is active. Continuous operation above the specified maximum operating junction temperature may impair device reliability.

Note 6: Duration of voltage transient is less than 20ns for each switching cycle.
TYPICAL PERFORMANCE CHARACTERISTICS

Load Regulation

![Load Regulation Graph]

ISET Current vs Temperature

![ISET Current vs Temperature Graph]

ISET Current vs VSET

![ISET Current vs VSET Graph]

ISET Current Line Regulation

![ISET Current Line Regulation Graph]

Quiescent Current vs Temperature

![Quiescent Current vs Temperature Graph]

Shutdown IQ vs VIN

![Shutdown IQ vs VIN Graph]

RDS(ON) vs Temperature

![RDS(ON) vs Temperature Graph]

ISET Current vs VISET

![ISET Current vs VISET Graph]

Typical Performance Characteristics

RDS(ON) vs Temperature

![RDS(ON) vs Temperature Graph]

Transient Response CCM Operation, External Compensation

![Transient Response CCM Operation, External Compensation Graph]

Transient Response CCM Operation, Internal Compensation

![Transient Response CCM Operation, Internal Compensation Graph]
**TYPICAL PERFORMANCE CHARACTERISTICS**

**Switch Leakage Current**

- $V_{IN} = 12V$
- $I_{SW} = 1MHz$
- $R_{TH} = 27.5k\Omega$, $C_{TH} = 250pF$
- $I_{OUT} = 0.1A$ TO $1A$
- $L = 4.7\mu H$
- $C_{OUT} = 47\mu F$

**INTVCC Load Regulation**

- $INTVCC = 5.0V$
- $INTVCC CURRENT (mA)$
- $INTVCC VOLTAGE (V)$
- Temperature (°C): $-50$ $-30$ $-10$ $0$ $10$ $20$ $30$ $40$ $50$ $60$ $70$ $80$ $90$ $100$
- Leakage Current (µA): $0$ $2$ $4$ $6$ $8$ $10$
- Temperature (°C): $-50$ $-30$ $-10$ $0$ $10$ $20$ $30$ $40$ $50$ $60$ $70$ $80$ $90$ $100$
TYPICAL PERFORMANCE CHARACTERISTICS

Rising RUN Threshold vs Temperature

Efficiency vs Load Current
V_{OUT} = 3.3V, V_{IN} = 12V

Efficiency vs Load Current
V_{OUT} = 1.2V, V_{IN} = 12V

Start-Up Waveform

V_{IN} Overvoltage

MODE = CCM
V_{OUT} IS PREBIASED TO 2V
V_{IN} = 12V
V_{OUT} = 3.3V

MODE = DCM
V_{OUT} IS PREBIASED TO 2V
V_{IN} = 12V
V_{OUT} = 3.3V

MODE = CCM
V_{IN} = 12V TO 18V TO 12V
V_{OUT} = 3.3V
I_{OUT} = 1A
V_{IN} RESISTOR = 30\Omega
MODE = CCM
**PIN FUNCTIONS**

**ISET (Pin 1):** Accurate 50µA Current Source. Positive input to the error amplifier. Connect an external resistor from this pin to signal GND to program the \( V_{OUT} \) voltage. Connecting an external capacitor from ISET to ground will soft start the output voltage and reduce current inrush when turning on. \( V_{OUT} \) can also be programmed by driving ISET directly with an external supply from 0 to \( V_{IN} \), in which case the external supply would be sinking the provided 50µA. Do not drive \( V_{ISET} \) above \( V_{IN} \) or below GND. Do not float ISET.

**ITH (Pin 2):** Error Amplifier Output and Switching Regulator Compensation Point. The internal current comparator’s trip threshold is linearly proportional to this voltage, whose normal range is from 0.3V to 2.4V. For external compensation, tie a resistor (\( R_{ITH} \)) in series with a capacitor (\( C_{ITH} \)) to signal GND. A separate 10pF high frequency filtering capacitor can also be placed from ITH to signal GND. Tying ITH to INTV\(_{CC}\) activates internal compensation.

**RT (Pin 3):** Switching Frequency Programming Pin. Connect an external resistor (between 200k to 10k) from RT to SGND to program the frequency from 200kHz to 4MHz. Tying the RT pin to INTV\(_{CC}\) programs 1MHz operation. Do not float the RT pin.

**PGFB (Pin 4):** Power Good Feedback. Place a resistor divider on \( V_{OUT} \) to detect power good level. If PGFB is more than 0.645V, or less than 0.555V, PGOOD will be pulled down. Tie PGFB to INTV\(_{CC}\) to disable the PGOOD function. Tying PGFB to a voltage greater than 0.64V and less than 4V will force continuous synchronous operation regardless of the MODE/SYNC state.

**RUN (Pin 5):** Run Control Input. Enables chip operation by tying RUN above 1.55V. Tying it below 1V shuts down the switching regulator. Tying it below 0.4V shuts off the entire chip. When tying RUN to more than 12V, place a resistor (100k to 500k) between RUN and the voltage source.

**MODE/SYNC (Pin 6):** Operation Mode Select. Tie this pin to INTV\(_{CC}\) to force continuous synchronous operation at all output loads. Tying it to GND enables discontinuous mode operation at light loads. Applying an external clock signal to this pin will synchronize switching frequency to the external clock. During external clock synchronization, \( R_{T} \) value should be set up such that the free running frequency is within 30% of the external clock frequency.

**SW (Pin 7):** Switch Node Connection to External Inductor. Voltage swing of SW is from a diode voltage drop below ground to \( V_{IN} \).

**V\(_{IN}\) (Pin 8):** Input voltage. Must decouple to GND with a capacitor close to the \( V_{IN} \) pin.

**BOOST (Pin 9):** Boosted Floating Driver Supply for Internal Top Power MOSFET. The (+) terminal of the bootstrap capacitor connects here. This pin swings from a diode voltage drop below INTV\(_{CC}\) up to \( V_{IN} + INTV_{CC} \).

**INTV\(_{CC}\) (Pin 10):** Internal 5V Regulator Output. The internal power drivers and control circuits are powered from this voltage. Decouple this pin to GND with a minimum of 1µF low ESR ceramic capacitor.

**V\(_{OUT}\) (Pin 11):** Output Voltage Pin. Output of the LTC3600 voltage regulator. Also the negative input of the error amplifier which is driven to be the same voltage as ISET.

**PGOOD (Pin 12):** Output Power Good with Open-Drain Logic. PGOOD is pulled to ground when the PGFB pin is more than 0.645V or less than 0.555V. PGOOD open-drain logic will be disabled if PGFB is tied to INTV\(_{CC}\).

**GND (Exposed Pad Pin 13):** Ground. Return path of internal power MOSFETs. Connect the exposed pad to the negative terminal of the input capacitor and output capacitor.
LTC3600

OPERATION

Main Control Loop

The LTC3600 is a current mode monolithic step down regulator. The accurate 50µA current source on the ISET pin allows the user to use just one external resistor to program the output voltage in a unity gain buffer fashion. In normal operation, the internal top power MOSFET is turned on for a fixed interval determined by a fixed one-shot timer OST. When the top power MOSFET turns off, the bottom power MOSFET turns on until the current comparator ICMP trips, restarting the one-shot timer and initiating the next cycle. Inductor current is determined by sensing the voltage drop across the SW and PGND nodes of the bottom power MOSFET. The voltage on the ITH pin sets the comparator threshold corresponding to inductor valley current. The error amplifier, EA, adjusts this ITH voltage by comparing the VOUT voltage with the voltage on ISET. If the load current increases, it causes a drop in the VOUT voltage relative to VISET. The ITH voltage then rises until the average inductor current matches that of the load current.

At low load current, the inductor current can drop to zero and become negative. This is detected by current reversal comparator, IREV, which then shuts off the bottom power MOSFET, resulting in discontinuous operation. Both power MOSFETs will remain off with the output capacitor supplying the load current until the ITH voltage rises above the zero current level (0.8V) to initiate another cycle. Discontinuous mode operation is disabled by tying the MODE pin to INTVCC, which forces continuous synchronous operation regardless of output load.

The operating frequency is determined by the value of the RT resistor, which programs the current for the internal oscillator as well as the current for the internal one-shot timer. An internal phase-locked loop servos the switching regulator on-time to track the internal oscillator to force constant switching frequency. If an external synchronization clock is present on the MODE/SYNC pin, the regulator on-time and switching frequency would then track the external clock.

Overvoltage and undervoltage comparators OV and UV pull the PGGOOD output low if the output power good feedback voltage VPGFB exits a 7.5% window around the regulation point. Continuous operation is forced during an OV condition. To defeat the PGGOOD function, simply tie PGFB to INTVCC.

Pulling the RUN pin to ground forces the LTC3600 into its shutdown state, turning off both power MOSFETs and all of its internal control circuitry. Bringing the RUN pin above 0.7V turns on the internal reference only, while still keeping the power MOSFETs off. Further increasing the RUN voltage above 1.5V turns on the entire chip.

INTVCC Regulator

An internal low drop out (LDO) regulator produces the 5V supply that powers the drivers and the internal bias circuitry. The INTVCC can supply up to 50mA RMS and must be bypassed to ground with a minimum of 1µF ceramic capacitor. Good bypassing is necessary to supply the high transient currents required by the power MOSFET gate drivers. Applications with high input voltage and high switching frequency will increase die temperature because of the higher power dissipation across the LDO. Connecting a load to the INTVCC pin is not recommended since it will further push the LDO into its RMS current rating while increasing power dissipation and die temperature.

VIN Overvoltage Protection

In order to protect the internal power MOSFET devices against transient voltage spikes, the LTC3600 constantly monitors the VIN pin for an overvoltage condition. When VIN rises above 16V, the regulator suspends operation by shutting off both power MOSFETs and discharges the ISET pin voltage to ground. Once VIN drops below 15V, the regulator immediately resumes normal switching operation by first charging up the ISET pin to its programmed voltage.

Programming Switching Frequency

Connecting a resistor from the RT pin to GND programs the switching frequency from 200kHz to 4MHz according to the following formula:

\[
\text{Frequency (Hz)} = \frac{3.6 \times 10^{10} (1/F)}{R_T (\Omega)}
\]

For ease of use, the RT pin can be connected directly to the INTVCC pin for 1MHz operation. Do not float the RT pin.

The internal on-time phase-locked loop has a synchronization range of 30% around its programmed frequency. Therefore, during external clock synchronization, the proper
**Operation**

RT value should be selected such that the external clock frequency is within this 30% range of the RT programmed frequency.

Output Voltage Tracking and Soft Start

The LTC3600 allows the user to program its output voltage ramp rate by means of the ISET pin. Since VOUT servos its voltage to that of the ISET pin, placing an external capacitor CSET on the ISET pin will program the ramp-up rate of the ISET pin and thus the VOUT voltage.

\[ V_{OUT(t)} = I_{SET} \cdot R_{SET} \left[ 1 - e^{-\frac{t}{R_{SET} \cdot C_{SET}}} \right] \]

from 0 to 90% VOUT

\[ t_{SS} \equiv -R_{SET} \cdot C_{SET} \cdot \ln(1 - 0.9) \]

\[ t_{SS} = 2.3R_{SET} \cdot C_{SET} \]

The soft-start time \( t_{SS} \) (from 0% to 90% \( V_{OUT} \)) is 2.3 times of time constant \((R_{SET} \cdot C_{SET})\). The ISET pin can also be driven by an external voltage supply capable of sinking 50µA.

When starting up into a pre-biased \( V_{OUT} \), the LTC3600 will stay in discontinuous mode and keep the power switches off until the voltage on ISET has ramped up to be equal to \( V_{OUT} \), at which point the switcher will begin switching and \( V_{OUT} \) will ramp up with ISET.

Output Power Good

When the LTC3600’s output voltage is within the 7.5% window of the regulation point, which is reflected back as a \( V_{PFB} \) voltage in the range of 0.555V to 0.645V, the output voltage is in regulation and the PGOOD pin is pulled high with an external resistor connected to INTVCC or another voltage rail. Otherwise, an internal open-drain pull-down device (200Ω) will pull the PGOOD pin low. To prevent unwanted PGOOD glitches during transients or dynamic \( V_{OUT} \) changes, the LTC3600’s PGOOD falling edge includes a blanking delay of approximately 20µs.

Internal/External ITH Compensation

For ease of use, the user can simplify the loop compensation by tying the ITH pin to INTVCC to enable internal compensation. This connects an internal 100k resistor in series with a 50pF capacitor to the output of the error amplifier (internal ITH compensation point). This is a trade-off for simplicity instead of OPTI-LOOP® optimization, where ITH components are external and are selected to optimize the loop transient response with minimum output capacitance.

Minimum Off-Time Considerations

The minimum off-time, \( t_{OFF(MIN)} \), is the smallest amount of time that the LTC3600 is capable of turning on the bottom power MOSFET, tripping the current comparator and turning the power MOSFET back off. This time is generally about 130ns. The minimum off-time limit imposes a maximum duty cycle of \( t_{ON}/(t_{ON} + t_{OFF(MIN)}) \). If the maximum duty cycle is reached, due to a dropping input voltage for example, then the output will drop out of regulation. The minimum input voltage to avoid dropout is:

\[ V_{IN(MIN)} = V_{OUT} \cdot \frac{t_{ON} + t_{OFF(MIN)}}{t_{ON}} \]

Conversely, the minimum on-time is the smallest duration of time in which the top power MOSFET can be in its “on” state. This time is typically 30ns. In continuous mode operation, the minimum on-time limit imposes a minimum duty cycle of:

\[ D_{MIN} = f_{SW} \cdot t_{ON(MIN)} \]

Where \( t_{ON(MIN)} \) is the minimum on-time. As the equation shows, reducing the operating frequency will alleviate the minimum duty cycle constraint.

In the rare cases where the minimum duty cycle is surpassed, the output voltage will still remain in regulation, but the switching frequency will decrease from its programmed value. This is an acceptable result in many applications, so this constraint may not be of critical importance in most cases. High switching frequencies may be used in the design without any fear of severe consequences. As the sections on inductor and capacitor selection show, high switching frequencies allow the use of smaller board components, thus reducing the size of the application circuit.
**APPLICATIONS INFORMATION**

**C\text{IN}** and **C\text{OUT}** Selection

The input capacitance, \( C_\text{IN} \), is needed to filter the trapezoidal wave current at the drain of the top power MOSFET. To prevent large voltage transients from occurring, a low ESR input capacitor sized for the maximum RMS current should be used. The maximum RMS current is given by:

\[
I_{\text{RMS}} = \frac{I_{\text{OUT}}(\text{MAX})}{\sqrt{V_{\text{OUT}}}} \frac{V_{\text{IN}} - V_{\text{OUT}}}{V_{\text{IN}}} - 1
\]

This formula has a maximum at \( V_{\text{IN}} = 2V_{\text{OUT}} \), where \( I_{\text{RMS}} = I_{\text{OUT}}/2 \). This simple worst-case condition is commonly used for design because even significant deviations do not offer much relief. Note that ripple current ratings from capacitor manufacturers are often based on only 2000 hours of life which makes it advisable to further derate the capacitor, or choose a capacitor rated at a higher temperature than required.

Several capacitors may also be paralleled to meet size or height requirements in the design. For low input voltage applications, sufficient bulk input capacitance is needed to minimize transient effects during output load changes.

The selection of \( C_\text{OUT} \) is determined by the effective series resistance (ESR) that is required to minimize voltage ripple and load step transients as well as the amount of bulk capacitance that is necessary to ensure that the control loop is stable. Loop stability can be checked by viewing the load transient response. The output ripple, \( \Delta V_{\text{OUT}} \), is determined by:

\[
\Delta V_{\text{OUT}} = \frac{\Delta I_L}{8 \cdot f_{\text{SW}} \cdot C_{\text{OUT}}} + \Delta I_L \cdot R_{\text{ESR}}
\]

The output ripple is highest at maximum input voltage since \( \Delta I_L \) increases with input voltage. Multiple capacitors placed in parallel may be needed to meet the ESR and RMS current handling requirements. Dry tantalum, special polymer, aluminum electrolytic and ceramic capacitors are all available in surface mount packages. Special polymer capacitors are very low ESR but have lower capacitance density than other types. Tantalum capacitors have the highest capacitance density but it is important to only use types that have been surge tested for use in switching power supplies. Aluminum electrolytic capacitors have significantly higher ESR, but can be used in cost-sensitive applications provided that consideration is given to ripple current ratings and long term reliability. Ceramic capacitors have excellent low ESR characteristics and small footprints. Their relatively low value of bulk capacitance may require multiples in parallel.

**Using Ceramic Input and Output Capacitors**

Higher values, lower cost ceramic capacitors are now becoming available in smaller case sizes. Their high ripple current, high voltage rating and low ESR make them ideal for switching regulator applications. However, care must be taken when these capacitors are used at the input and output. When a ceramic capacitor is used at the input and the power is supplied by a wall adapter through long wires, a load step at the output can induce ringing at the \( V_{\text{IN}} \) input. At best, this ringing can couple to the output and be mistaken as loop instability. At worst, a sudden inrush of current through the long wires can potentially cause a voltage spike at \( V_{\text{IN}} \) large enough to damage the part.

When choosing the input and output ceramic capacitors, choose the X5R and X7R dielectric formulations. These dielectrics have the best temperature and voltage characteristics of all the ceramics for a given value and size.

Since the ESR of a ceramic capacitor is so low, the input and output capacitor must instead fulfill a charge storage requirement. During a load step, the output capacitor must instantaneously supply the current to support the load until the feedback loop raises the switch current enough to support the load. The time required for the feedback loop to respond is dependent on the compensation and the output capacitor size. Typically, three to four cycles are required to respond to a load step, but only in the first cycle does the output drop linearly. The output droop, \( V_{\text{DROOP}} \), is usually about two to three times the linear drop of the first cycle. Thus, a good place to start with the output capacitor value is approximately:

\[
C_{\text{OUT}} = \frac{2.5 \cdot \Delta I_{\text{OUT}}}{f_{\text{SW}} \cdot V_{\text{DROOP}}}
\]

More capacitance may be required depending on the duty cycle and load step requirements.
In most applications, the input capacitor is merely required to supply high frequency bypassing, since the impedance to the supply is very low. A 22 µF ceramic capacitor is usually enough for these conditions. Place this input capacitor as close to $V_{IN}$ pin as possible.

**Inductor Selection**

Given the desired input and output voltages, the inductor value and operating frequency determine the ripple current:

$$\Delta I_L = \left( \frac{V_{OUT}}{f_{SW} \cdot L} \right) \left( 1 - \frac{V_{OUT}}{V_{IN}} \right).$$

Lower ripple current reduces core losses in the inductor, ESR losses in the output capacitors, and output voltage ripple. Highest efficiency operation is obtained at low frequency with small ripple current. However, achieving this requires a large inductor. There is a trade-off between component size, efficiency and operating frequency. A reasonable starting point is to choose a ripple current that is about 40% of $I_{OUT(\text{MAX})}$. Note that the largest ripple current occurs at the highest $V_{IN}$. To guarantee that ripple current does not exceed a specified maximum, the inductance should be chosen according to:

$$L = \left( \frac{V_{OUT}}{f_{SW} \cdot \Delta I_L(\text{MAX})} \right) \left( 1 - \frac{V_{OUT}}{V_{IN(\text{MAX})}} \right).$$

<table>
<thead>
<tr>
<th>Table 1. Inductor Selection Table</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>INDUCTOR</strong></td>
</tr>
<tr>
<td>IHLP-1616BZ-11 Series</td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td>IHLP-2020BZ-01 Series</td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td>FDV0620 Series</td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td>MPLC0525L Series</td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td>HCP0703 Series</td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td>RLF7030 Series</td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td>WE-TPC 4828 Series</td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
<tr>
<td></td>
</tr>
</tbody>
</table>
Once the value for L is known, the type of inductor must be selected. Ferrite designs have very low core losses and are preferred at high switching frequencies, so design goals can concentrate on copper loss and preventing saturation. Ferrite core material saturates “hard”, which means that inductance collapses abruptly when the peak design current is exceeded. This results in an abrupt increase in inductor ripple current and consequent output voltage ripple. Do not allow the core to saturate!

Different core materials and shapes will change the size/current and price/current relationship of an inductor. Toroid or shielded pot cores in ferrite or permalloy materials are small and do not radiate much energy, but generally cost more than powdered iron core inductors with similar characteristics. The choice of which style inductor to use mainly depends on the price versus size requirements and any radiated field/EMI requirements. New designs for surface mount inductors are available from Toko, Vishay, NEC/Tokin, Cooper, TDK, and Würth Elektronik. Refer to Table 1 for more details.

**Checking Transient Response**

The OPTI-LOOP compensation allows the transient response to be optimized for a wide range of loads and output capacitors. The availability of the ITH pin not only allows optimization of the control loop behavior but also provides a DC coupled and AC filtered closed loop response test point. The DC step, rise time and settling at this test point truly reflects the closed loop response. Assuming a predominantly second order system, phase margin and/or damping factor can be estimated using the percentage of overshoot seen at this pin.

The ITH external components shown in the Figure 1 circuit will provide an adequate starting point for most applications. The series R-C filter sets the dominant pole-zero loop compensation. The values can be modified slightly (from 0.5 to 2 times their suggested values) to optimize transient response once the final PC layout is done and the particular output capacitor type and value have been determined. The output capacitors need to be selected because their various types and values determine the loop feedback factor gain and phase. An output current pulse of 20% to 100% of full load current having a rise time of 1µs to 10µus will produce output voltage and ITH pin waveforms that will give a sense of the overall loop stability without breaking the feedback loop.

Switching regulators take several cycles to respond to a step in load current. When a load step occurs, VOUT immediately shifts by an amount equal to ΔLOAD • ESR, where ESR is the effective series resistance of COUT. ΔLOAD also begins to charge or discharge COUT generating a feedback error signal used by the regulator to return VOUT to its steady-state value. During this recovery time, VOUT can be monitored for overshoot or ringing that would indicate a stability problem.

The output voltage settling behavior is related to the stability of the closed-loop system and will demonstrate the actual overall supply performance. For a detailed explanation of optimizing the compensation components, including a review of control loop theory, refer to Linear Technology Application Note 76.

In some applications, a more severe transient can be caused by switching in loads with large (>10µF) load capacitors. The discharged load capacitors are effectively put in parallel with COUT, causing a rapid drop in VOUT. No regulator can deliver enough current to prevent this problem, if the switch connecting the load has low resistance and is driven quickly. The solution is to limit the turn-on speed of the load switch driver. A Hot Swap™ controller is designed specifically for this purpose and usually incorporates current limit, short-circuit protection, and soft-start.
Efficiency Considerations

The percent efficiency of a switching regulator is equal to the output power divided by the input power times 100%. It is often useful to analyze individual losses to determine what is limiting the efficiency and which change would produce the most improvement. Percent efficiency can be expressed as:

\[ \text{\% Efficiency} = 100\% - (L_1 + L_2 + L_3 + \ldots) \]

where \( L_1, L_2, \text{etc.} \), are the individual losses as a percentage of input power.

Although all dissipative elements in the circuit produce losses, four main sources usually account for most of the losses in LTC3600 circuits: 1) \( I^2R \) losses, 2) transition losses, 3) switching losses, 4) other losses.

1. \( I^2R \) losses are calculated from the DC resistances of the internal switches, \( R_{SW} \), the external inductor, \( R_L \), and board trace resistance, \( R_b \). In continuous mode, the average output current flows through inductor \( L \) but is “chopped” between the internal top and bottom power MOSFETs. Thus, the series resistance looking into the SW pin is a function of both top and bottom MOSFET \( R_{DS(ON)} \) and the duty cycle \( D \) as follows:

\[ R_{SW} = (R_{DS(ON)TOP})(D) + (R_{DS(ON)BOT})(1-D) \]

The \( R_{DS(ON)} \) for both the top and bottom MOSFETs can be obtained from the Typical Performance Characteristics curves. Thus, to obtain \( I^2R \) losses:

\[ I^2R \text{ losses} = I_{OUT}^2 (R_{SW} + R_L + R_b) \]

2. Transition loss arises from the brief amount of time the top power MOSFET spends in the saturated region during switch node transitions. It depends upon the input voltage, load current, internal power MOSFET gate capacitance, internal driver strength, and switching frequency.

3. The \( INTV_{CC} \) current is the sum of the power MOSFET driver and control currents. The power MOSFET driver current results from switching the gate capacitance of the power MOSFETs. Each time a power MOSFET gate is switched from low to high to low again, a packet of charge \( dQ \) moves from \( V_{IN} \) to ground. The resulting \( dQ/dt \) is a current out of \( INTV_{CC} \) that is typically much larger than the DC control bias current. In continuous mode, \( I_{GATECHG} = f_{SW} (QT + QB) \), where \( QT \) and \( QB \) are the gate charges of the internal top and bottom power MOSFETs and \( f_{SW} \) is the switching frequency. Since \( INTV_{CC} \) is a low dropout regulator output powered by \( V_{IN} \), the \( INTV_{CC} \) current also shows up as \( V_{IN} \) current, unless a separate voltage supply (>5V and <6V) is used to drive \( INTV_{CC} \).

4. Other “hidden” losses such as copper trace and internal load resistances can account for additional efficiency degradations in the overall power system. It is very important to include these system level losses in the design of a system. Other losses including diode conduction losses during dead-time and inductor core losses generally account for less than 2% total additional loss.

Thermal Considerations

In a majority of applications, the LTC3600 does not dissipate much heat due to its high efficiency and low thermal resistance of its exposed pad DFN or MSOP package. However, in applications where the LTC3600 is running at high ambient temperature, high \( V_{IN} \), high switching frequency and maximum output current load, the heat dissipated may exceed the maximum junction temperature of the part. If the junction temperature reaches approximately 160°C, both power switches will be turned off until temperature is about 15°C cooler.

To avoid the LTC3600 from exceeding the maximum junction temperature, the user will need to do some thermal analysis. The goal of the thermal analysis is to determine whether the power dissipated exceeds the maximum junction temperature of the part. The temperature rise is given by:

\[ T_{RISE} = P_D \cdot \theta_{JA} \]
As an example, consider the case when the LTC3600 is used in an application where \( V_{IN} = 12V \), \( I_{OUT} = 1.5A \), frequency = 4MHz, \( V_{OUT} = 1.8V \). The equivalent power MOSFET resistance \( R_{SW} \) is:

\[
R_{SW} = R_{DS(ON)TOP} \cdot \frac{V_{OUT}}{V_{IN}} + R_{DS(ON)BOT} \cdot \frac{V_{IN} - V_{OUT}}{V_{IN}} = 0.2 \cdot \frac{1.8}{12} + 0.1 \cdot \frac{10.2}{12} = 0.115 \Omega
\]

The \( V_{IN} \) current during 4MHz forced continuous operation with no load is about 11mA, which includes switching and internal biasing current loss, transition loss, inductor core loss and other losses in the application. Therefore, the total power dissipated by the part is:

\[
P_D = I_{OUT}^2 \cdot R_{SW} + V_{IN} \cdot I_{VIN} \text{ (No Load)} = 2.25A^2 \cdot 0.115\Omega + 12V \cdot 11mA = 0.39W
\]

The DFN 3mm x 3mm package junction-to-ambient thermal resistance, \( \theta_{JA} \), is around 55°C/W. Therefore, the junction temperature of the regulator operating in a 50°C ambient temperature is approximately:

\[
T_J = \frac{0.39W \cdot 55^\circ C}{W} + 50^\circ C = 71^\circ C
\]

Remembering that the above junction temperature is obtained from an \( R_{DS(ON)} \) at 25°C, we might recalculate the junction temperature based on a higher \( R_{DS(ON)} \) since it increases with temperature. Redoing the calculation assuming that \( R_{SW} \) increased 25% at 71°C yields a new junction temperature of 75°C, which is still very far away from thermal shutdown or maximum allowed junction temperature rating.

### Board Layout Considerations

When laying out the printed circuit board, the following checklist should be used to ensure proper operation of the LTC3600. Check the following in your layout:

1. Do the capacitors \( C_{IN} \) connect to the power \( V_{IN} \) and power GND as close as possible? These capacitors provide the AC current to the internal power MOSFETs and their drivers.

2. Are \( C_{OUT} \) and inductor closely connected? The (-) plate of \( C_{OUT} \) returns current to PGND and the (-) plate of \( C_{IN} \).

3. The ground terminal of the ISET resistor must be connected to the other quiet signal GND and together connect to the power GND on only one point. The ISET resistor should be placed and routed away from noisy components and traces, such as the SW line, and its trace should be minimized.

4. Keep sensitive components away from the SW pin. The ISET resistor, \( R_{TF} \) resistor, the compensation components \( C_{ITH} \) and \( R_{ITH} \), and the INTVCC bypass capacitor, should be routed away from the SW trace and the inductor.

5. A ground plane is preferred, but if not available, keep the signal and power grounds segregated with small signal components returning to the signal GND at one point which is then connected to the power GND at the exposed pad with minimal resistance.

Flood all unused areas on all layers with copper, which reduces the temperature rise of power components. These copper areas should be connected to one of the input supplies: \( V_{IN} \) or GND.
As a design example, consider using the LTC3600 in an application with the following specifications:

- $V_{\text{IN}} = 10.8\text{V} \text{ to } 13.2\text{V}$
- $V_{\text{OUT}} = 1.8\text{V}$
- $I_{\text{OUT (MAX)}} = 1.5\text{A}$
- $I_{\text{OUT (MIN)}} = 500\text{mA}$
- $f_{\text{SW}} = 2\text{MHz}$

First, $R_{\text{SET}}$ is selected based on:

$$R_{\text{SET}} = \frac{V_{\text{OUT}}}{50\mu\text{A}} = \frac{1.8\text{V}}{50\mu\text{A}} = 36\text{k}\Omega$$

For best accuracy, a 0.1% 36.1k resistor is selected.

Because efficiency is important at both high and low load current, discontinuous mode operation will be utilized. Select from the characteristic curves the correct $R_T$ resistor value for 2MHz switching frequency. Based on that, $R_T$ should be 18.2k. Then calculate the inductor value for about 40% ripple current at maximum $V_{\text{IN}}$:

$$L = \left(\frac{1.8\text{V}}{2\text{MHz} \cdot 0.6\text{A}}\right)\left(1 - \frac{1.8\text{V}}{13.2\text{V}}\right) = 1.3\mu\text{H}$$

The nearest standard value inductor would be 1.2µH.

$C_{\text{OUT}}$ will be selected based on the ESR that is required to satisfy the output voltage ripple requirement and the bulk capacitance needed for loop stability. For this design, one 47µF ceramic capacitor will be used.

$C_{\text{IN}}$ should be sized for a maximum current rating of:

$$I_{\text{RMS}} = 1.5\text{A} \left(\frac{1.8\text{V}}{13.2\text{V}}\right) \left(\frac{13.2\text{V}}{1.8\text{V}} - 1\right)^{1/2} = 0.51\text{A}$$

Decoupling the $V_{\text{IN}}$ pin with one 22µF ceramic capacitor is adequate for most applications.
Figure 1. 12V to 3.3V 1MHz Buck Regulator

12V to 1.2V 2MHz Buck Regulator
TYPICAL APPLICATIONS

0.9V FPGA Power Supply

*EXTERNAL CLOCK FOR FREQUENCY SYNCHRONIZATION IS RECOMMENDED

*Downloaded from Arrow.com.*
LTC3600

TYPICAL APPLICATIONS

High Efficiency Fast Load Response Power Supply

![Circuit Diagram]

- VIN
- ISET
- BOOST
- PWMC CONTROL AND SWITCH DRIVER
- SW
- LTC3600
- ERROR AMP
- MODE/ SYNC
- INTVCC
- RT
- PGBF
- ETH
- PGOOD
- LT3083
- VCONTROL
- SET
- OUT
- 2.52V 1.5A
- 4V TO 15V
- 50µA
- 10µF
- 100k
- 0.1µF
- 3.3V
- 56k
- 68pF
- 24.9k
- 10µF
- 3600 TA04
- 0.1µF
- 3.3V
- 8
- 5
- 7
- 9
- 11
- 12
- 6 10 3 4 2 12
- GND
- 22µF
- 2.2µH
- 68pF
- 56k
- 1µF
- 402Ω
- 3.3V

Downloaded from Arrow.com.
**TYPICAL APPLICATIONS**

**LED Driver with Programmable Dimming Control**

- Typical Applications
- LED Driver with Programmable Dimming Control
- 50µA
- 10µF
- 100k
- 0.1µF
- 22µF
- 10µH*

* TDK LTF5022T-100M1R4-LC
** LUXEON LXML-PWN1-0100

**High Efficiency 12V Audio Driver**

- Typical Applications
- High Efficiency 12V Audio Driver
- 30µA
- 10µF
- 120k
- 1µF
- 4.7µF
- 4.7µH
- 10µF

**Notes:**
- (LED CURRENT: 20mA TO 500mA)
- 0k TO 1k
- * TDK LTF5022T-100M1R4-LC
  ** LUXEON LXML-PWN1-0100
Programmable 1.5A Current Source

12V Fan Speed Controller

10k NTC THERMISTOR
MURATA NCP18XH103F03RB

*10k NTC THERMISTOR
MURATA NCP18XH103F03RB

Downloaded from Arrow.com.
15V, 3A Dual Phase Single-Output Regulator

Typical Applications

*EXTERNAL CLOCK FOR FREQUENCY SYNCHRONIZATION IS RECOMMENDED
TYPICAL APPLICATIONS

1.5A Lab Supply with Programmable Current Limit

IOUT = 0A TO 1.5A
VOUT = 0V TO 12V
0k TO 240k
GND
13
–
+
ERROR
AMP
–
+
ERROR
AMP

Downloaded from Arrow.com.
PACKAGE DESCRIPTION

Please refer to http://www.linear.com/product/LTC3600#packaging for the most recent package drawings.

DD Package
12-Lead Plastic DFN (3mm × 3mm)
(Reference LTC DWG # 05-08-1725 Rev A)

NOTE:
1. DRAWING IS NOT A JEDEC PACKAGE OUTLINE
2. DRAWING NOT TO SCALE
3. ALL DIMENSIONS ARE IN MILLIMETERS
4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.15mm ON ANY SIDE
5. EXPOSED PAD AND TIE BARS SHALL BE SOLDER PLATED
6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE

Please refer to http://www.linear.com/product/LTC3600#packaging for the most recent package drawings.
Please refer to http://www.linear.com/product/LTC3600#packaging for the most recent package drawings.

**MSE Package**

12-Lead Plastic MSOP, Exposed Die Pad

(Reference LTC DWG # 05-08-1666 Rev F)

**NOTE:**
1. DIMENSIONS IN MILLIMETER/(INCH)
2. DRAWING NOT TO SCALE
3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
   MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.152mm (.006") PER SIDE
4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
   INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.152mm (.006") PER SIDE
5. LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.102mm (.004") MAX
6. EXPOSED PAD DIMENSION DOES INCLUDE MOLD FLASH. MOLD FLASH ON E-PAD SHALL
   NOT EXCEED 0.254mm (.010") PER SIDE.
## Revision History

<table>
<thead>
<tr>
<th>REV</th>
<th>DATE</th>
<th>Description</th>
<th>PAGE NUMBER</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>03/12</td>
<td>Clarified Feature and Description</td>
<td>1</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Clarified Electrical Characteristics</td>
<td>3</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Clarified ISET (Pin 1) Description</td>
<td>8</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Clarified Functional Diagram</td>
<td>9</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Modified Application Circuit</td>
<td>28</td>
</tr>
<tr>
<td>B</td>
<td>04/12</td>
<td>Changed MODE/SYNC Threshold SYNC $V_{H(MIN)}$ from 1V to 2.5V</td>
<td>3</td>
</tr>
<tr>
<td>C</td>
<td>07/12</td>
<td>Clarified Supply Shutdown Current to Zero</td>
<td>1</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Clarified Absolute Maximum Ratings to include Note 5</td>
<td>2</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Clarified Conditions on Electrical Table, $V_{IN} = 12V$</td>
<td>3</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Clarified Pin Functions</td>
<td>8</td>
</tr>
<tr>
<td>D</td>
<td>06/16</td>
<td>Revised Minimum Off Time Considerations section</td>
<td>11</td>
</tr>
</tbody>
</table>
# LTC3600

## TYPICAL APPLICATION

High Efficiency, Low Noise 1A Supply

![Diagram of LTC3600 circuit](image)

### RELATED PARTS

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>DESCRIPTION</th>
<th>COMMENTS</th>
</tr>
</thead>
<tbody>
<tr>
<td>LTC3601</td>
<td>15V, 1.5A (i_{OUT}), 4MHz, Synchronous Step-Down DC/DC Converter</td>
<td>95% Efficiency, (V_{IN}) 4.5V to 15V, (V_{OUT(MIN)}) = 0.6V, (I_{O} = 300\mu A, I_{SD} &lt; 1\mu A, 4mm \times 4mm QFN-20 and MSOP-16E Packages</td>
</tr>
<tr>
<td>LTC3603</td>
<td>15V, 2.5A (i_{OUT}), 3MHz, Synchronous Step-Down DC/DC Converter</td>
<td>95% Efficiency, (V_{IN}) 4.5V to 15V, (V_{OUT(MIN)}) = 0.6V, (I_{O} = 75\mu A, I_{SD} &lt; 1\mu A, 4mm \times 4mm QFN-20 and MSOP-16E Packages</td>
</tr>
<tr>
<td>LTC3633</td>
<td>15V, Dual 3A (i_{OUT}), 4MHz, Synchronous Step-Down DC/DC Converter</td>
<td>95% Efficiency, (V_{IN}) 3.6V to 15V, (V_{OUT(MIN)}) = 0.6V, (I_{O} = 500\mu A, I_{SD} &lt; 15\mu A, 4mm \times 5mm QFN-28 and TSSOP-28E Packages</td>
</tr>
<tr>
<td>LTC3605</td>
<td>15V, 5A (i_{OUT}), 4MHz, Synchronous Step-Down DC/DC Converter</td>
<td>95% Efficiency, (V_{IN}) 4V to 15V, (V_{OUT(MIN)}) = 0.6V, (I_{O} = 2mA, I_{SD} &lt; 15\mu A, 4mm \times 4mm QFN-24 and MSOP-16E Packages</td>
</tr>
<tr>
<td>LTC3604</td>
<td>15V, 2.5A (i_{OUT}), 4MHz, Synchronous Step-Down DC/DC Converter</td>
<td>95% Efficiency, (V_{IN}) 3.6V to 15V, (V_{OUT(MIN)}) = 0.6V, (I_{O} = 300\mu A, I_{SD} &lt; 14\mu A, 3mm \times 3mm QFN-16 and MSOP-16E Packages</td>
</tr>
<tr>
<td>LT3080</td>
<td>1.1A, Parallelable, Low Noise, Low Dropout Linear Regulator</td>
<td>300mV Dropout Voltage (2 Supply Operation), Low Noise = 40µVRMS (V_{IN}) 1.2V to 36V, (V_{OUT}) 0V to 35.7V, MSOP-8, 3mm \times 3mm DFN Packages</td>
</tr>
<tr>
<td>LT3083</td>
<td>Adjustable 3A Single Resistor Low Dropout Regulator</td>
<td>310mV Dropout Voltage, Low Noise 40µVRMS (V_{IN}) 1.2V to 23V, (V_{OUT}) 0V to 22.7V, 4mm \times 4mm DFN, TSSOP-16E Packages</td>
</tr>
</tbody>
</table>